

09719844

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NEWS 3 Jan 29 FSTA has been reloaded and moves to weekly updates  
NEWS 4 Feb 01 DKILIT now produced by FIZ Karlsruhe and has a new update  
frequency  
NEWS 5 Feb 19 Access via Tymnet and SprintNet Eliminated Effective 3/31/02  
NEWS 6 Mar 08 Gene Names now available in BIOSIS  
NEWS 7 Mar 22 TOXLIT no longer available  
NEWS 8 Mar 22 TRCTHERMO no longer available  
NEWS 9 Mar 28 US Provisional Priorities searched with P in CA/CAPLUS  
and USPATFULL  
NEWS 10 Mar 28 LIPINSKI/CALC added for property searching in REGISTRY  
NEWS 11 Apr 02 PAPERCHEM no longer available on STN. Use PAPERCHEM2 instead.  
NEWS 12 Apr 08 "Ask CAS" for self-help around the clock  
NEWS 13 Apr 09 BEILSTEIN: Reload and Implementation of a New Subject Area  
NEWS 14 Apr 09 ZDB will be removed from STN  
NEWS 15 Apr 19 US Patent Applications available in IFICDB, IFIPAT, and IFIUDB  
NEWS 16 Apr 22 Records from IP.com available in CAPLUS, HCAPLUS, and ZCAPLUS  
NEWS 17 Apr 22 BIOSIS Gene Names now available in TOXCENTER  
NEWS 18 Apr 22 Federal Research in Progress (FEDRIP) now available  
  
NEWS EXPRESS February 1 CURRENT WINDOWS VERSION IS V6.0d,  
CURRENT MACINTOSH VERSION IS V6.0a(ENG) AND V6.0Ja(JP),  
AND CURRENT DISCOVER FILE IS DATED 05 FEBRUARY 2002  
  
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NEWS PHONE Direct Dial and Telecommunication Network Access to STN  
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COST IN U.S. DOLLARS  
  
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| ENTRY      | SESSION |
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STRUCTURE FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4  
DICTIONARY FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4

TSCA INFORMATION NOW CURRENT THROUGH July 7, 2001

Please note that search-term pricing does apply when  
conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Calculated physical property data is now available. See HELP PROPERTIES  
for more information. See STNote 27, Searching Properties in the CAS  
Registry File, for complete details:  
<http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf>

=>

Uploading 09543628.str

L1 STRUCTURE UPLOADED

=> s full l1

FULL SEARCH INITIATED 18:22:23 FILE 'REGISTRY'  
FULL SCREEN SEARCH COMPLETED - 1126 TO ITERATE

100.0% PROCESSED 1126 ITERATIONS 815 ANSWERS  
SEARCH TIME: 00.00.01

L2 815 SEA SSS FUL L1

=> file caplus

| COST IN U.S. DOLLARS | SINCE FILE<br>ENTRY | TOTAL<br>SESSION |
|----------------------|---------------------|------------------|
| FULL ESTIMATED COST  | 140.28              | 140.49           |

FILE 'CAPLUS' ENTERED AT 18:22:31 ON 13 MAY 2002  
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FILE COVERS 1907 - 13 May 2002 VOL 136 ISS 20  
FILE LAST UPDATED: 10 May 2002 (20020510/ED)

This file contains CAS Registry Numbers for easy and accurate  
substance identification.

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CAS roles have been modified effective December 16, 2001. Please check your SDI profiles to see if they need to be revised. For information on CAS roles, enter HELP ROLES at an arrow prompt or use the CAS Roles thesaurus (/RL field) in this file.

=> s electronic and l2  
363585 ELECTRONIC  
21498 ELECTRONICS  
378840 ELECTRONIC  
(ELECTRONIC OR ELECTRONICS)  
1391 L2  
L3 56 ELECTRONIC AND L2

=> s l3 and (adhesive or adhesion)  
141668 ADHESIVE  
92659 ADHESIVES  
160378 ADHESIVE  
(ADHESIVE OR ADHESIVES)  
200551 ADHESION  
2593 ADHESIONS  
201407 ADHESION  
(ADHESION OR ADHESIONS)  
L4 11 L3 AND (ADHESIVE OR ADHESION)

=> d ibib abs hitstr 1

L4 ANSWER 1 OF 11 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 2001:692309 CAPLUS  
DOCUMENT NUMBER: 135:243394  
TITLE: Die-attaching polyurethane acrylate **adhesive**  
paste compositions with fast-curing character for  
semiconductor devices  
INVENTOR(S): Kagimoto, Yoshihiro  
PATENT ASSIGNEE(S): Sumitomo Bakelite Co., Ltd., Japan  
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.  
CODEN: JKXXAF  
DOCUMENT TYPE: Patent  
LANGUAGE: Japanese  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

|    | PATENT NO.  | KIND | DATE     | APPLICATION NO. | DATE     |
|----|---|------|----------|-----------------|----------|
|    | -----   | ---- | -----    | -----           | -----    |
|    | JP 2001257220   | A2   | 20010921 | JP 2000-68099   | 20000313 |
| AB | Title compn. comprises (A) urethane di(meth)acrylate derived from polyalkylene glycol, diisocyanate, and hydroxyalkyl (meth)acrylic acid, (B) (meth)acryl group-contg. reactive diluent, (C) triglycidyl isocyanurate, (D) phosphoric acid group-contg. (meth)acrylate, (E) epoxy alkoxysilane, (F) org. peroxide and/or azo compd., (G) inorg. filler, wherein the wt. ratio of F/(A + B + C) = 0.1-5%. Thus, a compn. comprising Aronix M-1600 45, diethylene glycol monoacrylate Ph ether 45, T.E.P.I.C. 10, cumyl peroxyneodecanoate 0.5, Kayamer PM 21 1, KMB 303 0.5, and powd. Ag 300 parts was kneaded to give a conductive paste exhibiting good stability, workability, and fast curing property. |      |          |                 |          |
| IT | <b>360796-01-6P 360796-02-7P 360796-03-8P</b><br>RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)<br>(manuf. of polyurethane acrylate die-attaching <b>adhesive</b> paste with fast-curing character for semiconductor devices)  |      |          |                 |          |
| RN | 360796-01-6 CAPLUS  |      |          |                 |          |
| CN | Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester,   |      |          |                 |          |

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phosphate, polymer with Aronix M 1600, 2-(2-phenoxyethoxy)ethyl  
2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and  
1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI)  
(CA INDEX NAME)

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CRN 100629-45-6

CMF Unspecified

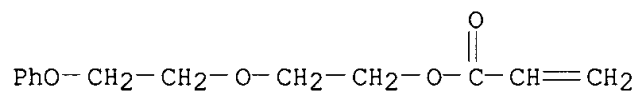
CCI MAN

\*\*\* STRUCTURE DIAGRAM IS NOT AVAILABLE \*\*\*

CM 2

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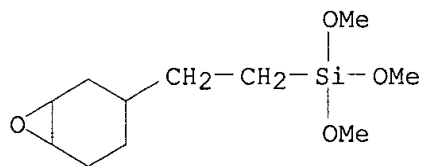
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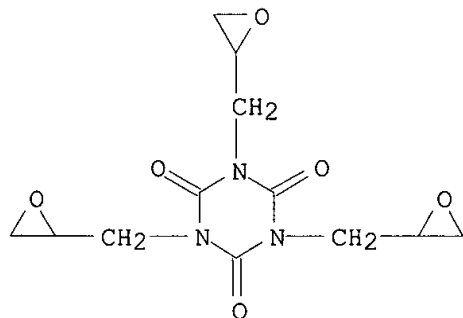
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CM 4

CRN 2451-62-9

CMF C12 H15 N3 O6



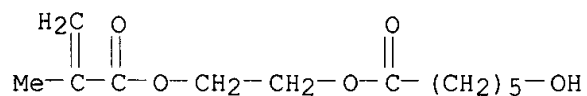
CM 5

09719844

CRN 103370-83-8  
CMF C12 H20 O5 . x H3 O4 P  
CDES 8:GD,ESTER

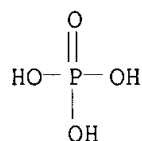
CM 6

CRN 85099-10-1  
CMF C12 H20 O5



CM 7

CRN 7664-38-2  
CMF H3 O4 P



RN 360796-02-7 CAPLUS  
CN Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester, phosphate, polymer with Aronix M 1600, 2-([1,1'-biphenyl]-4-yloxy)ethyl 2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and 1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

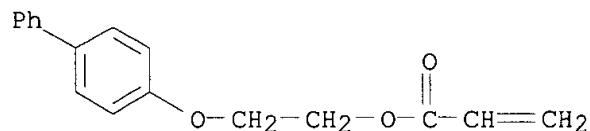
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CRN 100629-45-6  
CMF Unspecified  
CCI MAN

\*\*\* STRUCTURE DIAGRAM IS NOT AVAILABLE \*\*\*

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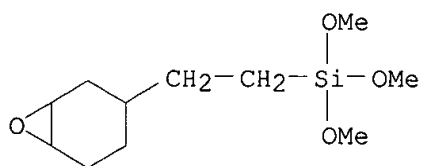
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CMF C17 H16 O3



CM 3

CRN 3388-04-3  
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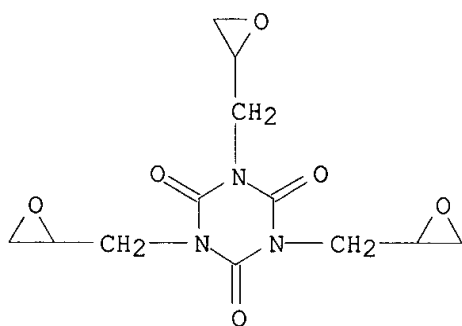
09719844



CM 4

CRN 2451-62-9

CMF C12 H15 N3 O6



CM 5

CRN 103370-83-8

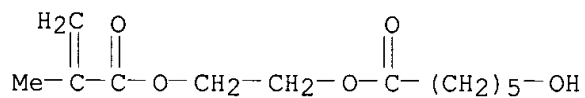
CMF C12 H20 O5 . x H3 O4 P

CDES 8:GD,ESTER

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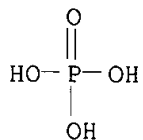
CMF C12 H20 O5



CM 7

CRN 7664-38-2

CMF H3 O4 P



09719844

RN 360796-03-8 CAPLUS

CN Hexanoic acid, 6-hydroxy-, 2-[(2-methyl-1-oxo-2-propenyl)oxy]ethyl ester, phosphate, polymer with Aronix M 1600, (octahydro-4,7-methano-1H-indene-5,7-diyl)bis(methylene) di-2-propenoate, trimethoxy[2-(7-oxabicyclo[4.1.0]hept-3-yl)ethyl]silane and 1,3,5-tris(oxiranylmethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 100629-45-6

CMF Unspecified

CCI MAN

\*\*\* STRUCTURE DIAGRAM IS NOT AVAILABLE \*\*\*

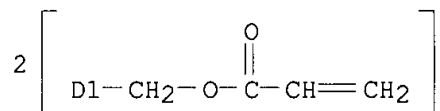
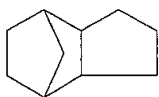
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CRN 42594-17-2

CMF C18 H24 O4

CCI IDS

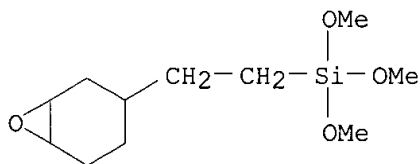
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CM 3

CRN 3388-04-3

CMF C11 H22 O4 Si

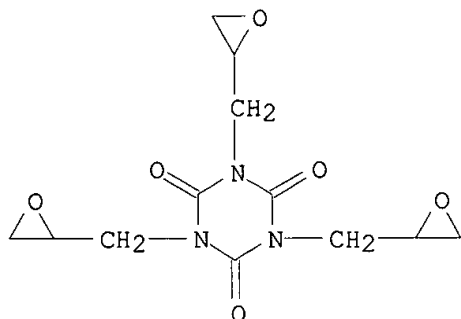


CM 4

CRN 2451-62-9

CMF C12 H15 N3 O6

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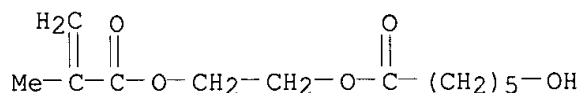


CM 5

CRN 103370-83-8  
CMF C12 H20 O5 . x H3 O4 P  
CDES 8:GD,ESTER

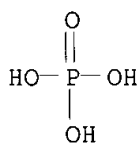
CM 6

CRN 85099-10-1  
CMF C12 H20 O5



CM 7

CRN 7664-38-2  
CMF H3 O4 P



=> d ibib abs hitstr 2

L4 ANSWER 2 OF 11 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 2000:268555 CAPLUS  
DOCUMENT NUMBER: 132:309393  
TITLE: Curable compositions and **adhesive**  
compositions for manufacture of circuit parts and  
printed circuit boards  
INVENTOR(S): Tong, Quinn K.; Ma, Bodan; Xiao, Chaodong  
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corp.,  
USA  
SOURCE: Jpn. Kokai Tokkyo Koho, 111 pp.  
CODEN: JKXXAF  
DOCUMENT TYPE: Patent  
LANGUAGE: Japanese



09719844

FAMILY ACC. NUM. COUNT: 2

PATENT INFORMATION:

| PATENT NO.    | KIND | DATE     | APPLICATION NO. | DATE     |
|---------------|------|----------|-----------------|----------|
| JP 2000119335 | A2   | 20000425 | JP 1999-188845  | 19990702 |
| US 6281314    | B1   | 20010828 | US 1999-336324  | 19990618 |
| CN 1245181    | A    | 20000223 | CN 1999-119203  | 19990630 |
| KR 2000011442 | A    | 20000225 | KR 1999-26615   | 19990702 |

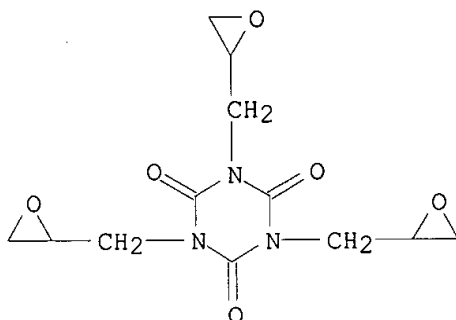
PRIORITY APPLN. INFO.: US 1998-91490P P 19980702  
US 1999-336324 A 19990618

AB Title curable compns. contain (A) maleimides and (B) curing initiators consisting of free-radical initiators and/or photopolymn. initiators. Title **adhesive** compns. contain (C) vinyl compds. and B. Markush structures of A and C are given in the document. Thus, a compn. contg. Versalink P 650 (bismaleimide), cyclohexanedimethanol divinyl ether, and Irgacure 651 (.alpha.,.alpha.-dimethoxy-.alpha.-phenylacetophenone) was irradiated with UV light to bond a Si die.

IT **2451-62-9**, Tris(epoxypropyl) isocyanurate  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(maleimide-contg. photocurable **adhesive** compns. for manuf. of printed circuit boards)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI)  
(CA INDEX NAME)



=> d ibib abs hitstr 3

L4 ANSWER 3 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 2000:12715 CAPLUS

DOCUMENT NUMBER: 132:79493

TITLE: Die attach **adhesives** for use in microelectronics

INVENTOR(S): Herr, Donald; Schultz, Rose Ann; Xu, Ping Yong

PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corp., USA

SOURCE: Eur. Pat. Appl., 44 pp.

CODEN: EPXXDW

DOCUMENT TYPE: Patent

LANGUAGE: English

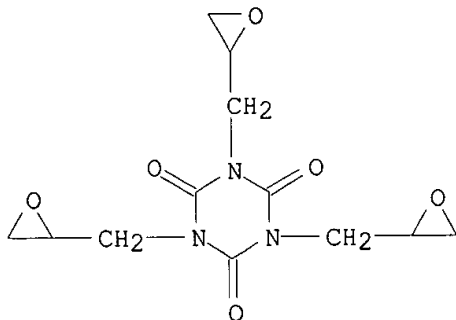
FAMILY ACC. NUM. COUNT: 3

PATENT INFORMATION:

| PATENT NO. | KIND | DATE     | APPLICATION NO. | DATE     |
|------------|------|----------|-----------------|----------|
| EP 969065  | A2   | 20000105 | EP 1999-112734  | 19990701 |

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EP 969065 A3 20000223  
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,  
IE, SI, LT, LV, FI, RO  
US 6265530 B1 20010724 US 1999-336245 19990618  
CN 1248603 A 20000329 CN 1999-111395 19990630  
JP 2000044888 A2 20000215 JP 1999-189198 19990702  
KR 2000011449 A 20000225 KR 1999-26638 19990702  
US 2002007042 A1 20020117 US 2001-773800 20010201  
PRIORITY APPLN. INFO.: US 1998-91492P P 19980702  
US 1999-336245 A 19990618  
AB A curable **adhesive** compn. for use in bonding an  
**electronic** component to a substrate comprises a maleimide compd.  
and a curing initiator selected from the group consisting of a  
free-radical initiator, a photoinitiator, and a combination of those.  
IT **2451-62-9**, Tris(epoxypropyl)isocyanurate  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(die attach **adhesives** for use in microelectronics)  
RN 2451-62-9 CAPLUS  
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI)  
(CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS  
RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

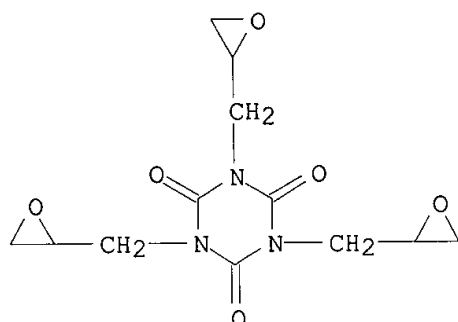
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L4 ANSWER 4 OF 11 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 2000:12713 CAPLUS  
DOCUMENT NUMBER: 132:79491  
TITLE: Package encapsulant compositions for use in  
**electronic** devices  
INVENTOR(S): Ma, Bodan; Tong, Quinn K.  
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding  
Corporation, USA  
SOURCE: Eur. Pat. Appl., 45 pp.  
CODEN: EPXXDW  
DOCUMENT TYPE: Patent  
LANGUAGE: English  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

| PATENT NO.   | KIND | DATE     | APPLICATION NO. | DATE     |
|--|------|----------|-----------------|----------|
| EP 969063  | A2   | 20000105 | EP 1999-112725  | 19990701 |
| EP 969063  | A3   | 20000223 |                 |          |
| R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,<br>IE, SI, LT, LV, FI, RO |      |          |                 |          |

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US 6316566 B1 20011113 US 1999-336246 19990618  
CN 1244562 A 20000216 CN 1999-119202 19990630  
KR 2000011447 A 20000225 KR 1999-26624 19990702  
JP 2000103817 A2 20000411 JP 1999-189376 19990702  
US 2001056162 A1 20011227 US 2001-894540 20010628  
PRIORITY APPLN. INFO.: US 1998-91493P P 19980702  
US 1999-336246 A 19990618  
AB A curable package encapsulant compn. comprises a maleimide compd. and a  
curing initiator selected from the group consisting of a free-radical  
initiator, a photoinitiator, and a combination of those.  
IT **2451-62-9**, Tris(epoxypropyl)isocyanurate  
RL: RCT (Reactant); RACT (Reactant or reagent)  
(package encapsulant compns. for use in **electronic** devices)  
RN 2451-62-9 CAPLUS  
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI)  
(CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS  
RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 5

L4 ANSWER 5 OF 11 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 2000:12712 CAPLUS  
DOCUMENT NUMBER: 132:79440  
TITLE: Method of making **electronic** components using  
reworkable **adhesives**  
INVENTOR(S): Tong, Quinn K.; Ma, Bodan; Xiao, Chaodong; Shenfield,  
David  
PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding  
Corporation, USA  
SOURCE: Eur. Pat. Appl., 44 pp.  
CODEN: EPXXDW  
DOCUMENT TYPE: Patent  
LANGUAGE: English  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

| PATENT NO.   | KIND | DATE     | APPLICATION NO.  | DATE     |
|--|------|----------|------------------|----------|
| EP 969062  | A2   | 20000105 | EP 1999-112724   | 19990701 |
| EP 969062  | A3   | 20000223 |                  |          |
| R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,<br>IE, SI, LT, LV, FI, RO |      |          |                  |          |
| CN 1243141   | A    | 20000202 | CN 1999-111479   | 19990630 |
| JP 2000086978  | A2   | 20000328 | JP 1999-189698   | 19990702 |
| PRIORITY APPLN. INFO.:   |      |          | US 1998-91506P P | 19980702 |

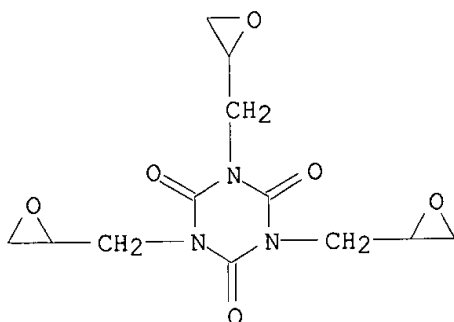
US 1999-335809 A 19990618

AB A method for making an **electronic** component adhered to a substrate with a cured reworkable **adhesive** compn. comprises: (a) providing a curable reworkable **adhesive** compn. comprising (i) one or more mono-functional vinyl compds. in a major amt. effective to provide thermoplastic properties, and (ii) optionally, one or more polyfunctional vinyl compds. in a minor amt. ineffective to diminish the thermoplastic properties of the cured compn., (iii) a curing initiator selected from the group consisting of a radical initiator, a photoinitiator, and a combination of those, (iv) optionally, one or more fillers; (v) optionally, one or more **adhesion** promoters; (b) applying the curable reworkable **adhesive** compn. to either the **electronic** component or the substrate (c) contacting the **electronic** component and the substrate together; and (d) curing the compn. in situ.

IT **2451-62-9**, Tris(epoxypropyl)isocyanurate  
 RL: RCT (Reactant); RACT (Reactant or reagent)  
 (method of making **electronic** components using reworkable **adhesives**)

RN **2451-62-9** CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI)  
 (CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 6

L4 ANSWER 6 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 2000:12708 CAPLUS

DOCUMENT NUMBER: 132:79488

TITLE: Method of making encapsulated **electronic** component with reworkable package encapsulants

INVENTOR(S): Ma, Bodan; Tong, Quinn K.; Xiao, Chaodong

PATENT ASSIGNEE(S): National Starch and Chemical Investment Holding Corporation, USA

SOURCE: Eur. Pat. Appl., 30 pp.

CODEN: EPXXDW

DOCUMENT TYPE: Patent

LANGUAGE: English

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

| PATENT NO. | KIND | DATE     | APPLICATION NO. | DATE     |
|------------|------|----------|-----------------|----------|
| -----      | ---- | -----    | -----           | -----    |
| EP 969058  | A2   | 20000105 | EP 1999-112719  | 19990701 |
| EP 969058  | A3   | 20000223 |                 |          |

09719844

R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT,  
IE, SI, LT, LV, FI, RO

|               |    |          |                |          |
|---------------|----|----------|----------------|----------|
| CN 1254182    | A  | 20000524 | CN 1999-111271 | 19990630 |
| KR 2000011414 | A  | 20000225 | KR 1999-26329  | 19990701 |
| JP 2000036505 | A2 | 20000202 | JP 1999-189331 | 19990702 |

PRIORITY APPLN. INFO.: US 1998-109189 A 19980702

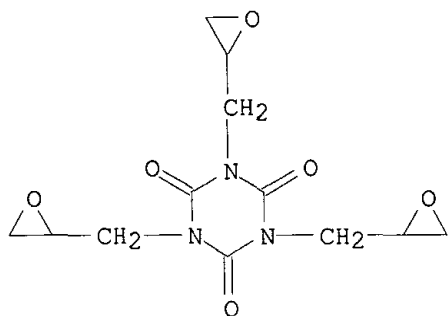
AB Encapsulated **electronic** components are manufd. by using reworkable encapsulants prepd. from in-situ-curable compns. contg. mono- and(or) polyfunctional maleimide compds. or mono- and(or) polyfunctional vinyl compds. other than maleimide compds. or a combination of the maleimide and vinyl compds., a curing initiator, and, optionally, or .gtoreq.1 filler or **adhesion** promoter. A typical encapsulant compn. contained Versalink P-650 (bismaleimide prepd. from polytetramethylene glycol di-p-aminobenzoate) 1.01, cyclohexanedimethanol divinyl ether 0.19, Irgacure 651 0.06, and hydrophilic fused silica 3.78 g.

IT **2451-62-9**, Triglycidyl isocyanurate

RL: RCT (Reactant); RACT (Reactant or reagent)  
(encapsulant component precursor; making encapsulated **electronic** components with reworkable package encapsulants from compns. contg. maleimide and vinyl compds.)

RN 2451-62-9 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)- (9CI)  
(CA INDEX NAME)



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 7

L4 ANSWER 7 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:788216 CAPLUS

DOCUMENT NUMBER: 132:36659

TITLE: Epoxy resin compositions with excellent mold releasability and optical semiconductor devices sealed therewith

INVENTOR(S): Tsuchida, Satoru; Kosaka, Masahiko

PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

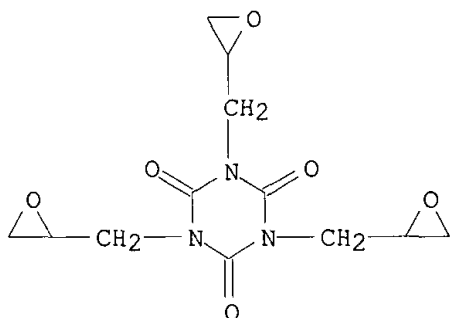
| PATENT NO. | KIND | DATE  | APPLICATION NO. | DATE  |
|------------|------|-------|-----------------|-------|
| -----      | ---- | ----- | -----           | ----- |

09719844

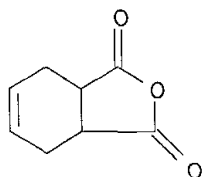
JP 11343395      A2    19991214      JP 1998-152899    19980602  
AB    The compns. contain epoxy resins and  $\text{MeCH}_2(\text{CH}_2\text{CH}_2)_m\text{CH}_2\text{CO}(\text{OCH}_2\text{CH}_2)_n\text{OH}$  (I;  $m = 5-30$ ;  $n = 2-40$ ;  $n/m = 0.1-3$ ). Thus, a compn. contg. Epomik R 366 (bisphenol A epoxy resin) 80, TEPIC-S (multifunctional epoxy resin) 20, Rikacid TH (tetrahydrophthalic anhydride) 38, and I ( $m = 15$ ,  $n = 10$ ) 1.5 parts was transfer molded and cured to give a test piece showing light transmittance 90% at 600 nm and good **adhesion** to an Al foil and mold releasability after 20 shots.  
IT    **209804-91-1P**  
      RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)  
          (epoxy resin compns. with good mold releasability and **adhesion** to metals for sealing optical semiconductor devices)  
RN    209804-91-1    CAPLUS  
CN    1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with Epomik R 366 and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)  
  
CM    1  
  
CRN   143550-01-0  
CMF   Unspecified  
CCI   PMS, MAN

\*\*\* STRUCTURE DIAGRAM IS NOT AVAILABLE \*\*\*

CM    2  
  
CRN   2451-62-9  
CMF   C12 H15 N3 O6



CM    3  
  
CRN   85-43-8  
CMF   C8 H8 O3



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L4 ANSWER 8 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:731776 CAPLUS

DOCUMENT NUMBER: 131:352273

TITLE: Epoxy resin compositions containing polyether-modified silicone oils for packaging photosemiconductor devices

INVENTOR(S): Tsuchida, Satoru; Osaka, Masahiko

PATENT ASSIGNEE(S): Htiachi Chemical Company, Ltd., Japan

SOURCE: U.S., 7 pp.

CODEN: USXXAM

DOCUMENT TYPE: Patent

LANGUAGE: English

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

|    | PATENT NO.   | KIND | DATE     | APPLICATION NO. | DATE     |
|----|--|------|----------|-----------------|----------|
|    | US 5985954   | A    | 19991116 | US 1997-985208  | 19971202 |
| AB | The compn. having good releasability <b>adhesion</b> to metals and light transmittance, comprises (A) an epoxy resin [e.g., Epomik R 366 (bisphenol A epoxy resin) and Tepic-S (triglycidyl isocyanurate homopolymer)], (B) a curing agent [Rikacid TH (tetrahydrophthalic anhydride)] and (C) a polyether-modified silicone oil (CH <sub>3</sub> ) <sub>3</sub> SiO[SiO(CH <sub>3</sub> ) <sub>2</sub> ]m{SiO(CH <sub>3</sub> )[C <sub>3</sub> H <sub>6</sub> O(C <sub>2</sub> H <sub>4</sub> O)a(C <sub>3</sub> H <sub>6</sub> O)bR]}nSi(CH <sub>3</sub> ) <sub>3</sub> (m, n, a .gtoreq.1; b .gtoreq.0; R = H, C1-6 alkyl) having wt. av. mol. wt. 1,000-100,000, silicone unit content {[m+n+2]/(m+n+2+a+b+1)}.times.100} 10-60% and polyether unit content {[a+b+1]/(m+n+2+a+b+1)}.times.100} 40-90%. |      |          |                 |          |
| IT | <b>209804-91-1P</b><br>RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (epoxy resin compns. contg. polyoxyakylene-modified silicone oils for packaging photosemiconductor devices)   |      |          |                 |          |
| RN | 209804-91-1 CAPLUS   |      |          |                 |          |
| CN | 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with Epomik R 366 and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)  |      |          |                 |          |

CM 1

CRN 143550-01-0

CMF Unspecified

CCI PMS, MAN

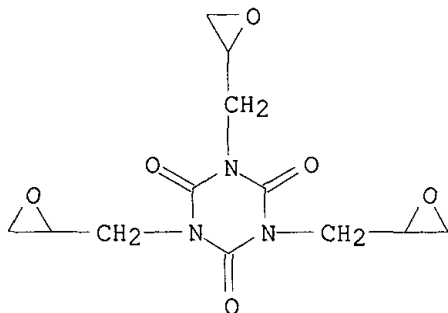
\*\*\* STRUCTURE DIAGRAM IS NOT AVAILABLE \*\*\*

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CRN 2451-62-9

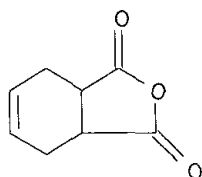
CMF C12 H15 N3 O6

09719844



CM 3

CRN 85-43-8  
CMF C8 H8 O3



REFERENCE COUNT: 1 THERE ARE 1 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d ibib abs hitstr 9

L4 ANSWER 9 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:699200 CAPLUS

DOCUMENT NUMBER: 131:323593

TITLE: Epoxy resin compositions having good mold release properties and **adhesion** for packaging optical semiconductor devices

INVENTOR(S): Noro, Masato; Komada, Shigeya; Shimata, Katsumi; Okuda, Satoru; Uenishi, Shinjiro; Hattori, Kuniharu

PATENT ASSIGNEE(S): Nitto Denko Corp., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 11 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

| PATENT NO.  | KIND | DATE     | APPLICATION NO.  | DATE     |
|-------------|------|----------|------------------|----------|
| JP 11302499 | A2   | 19991102 | JP 1998-112589   | 19980423 |
| US 6221510  | B1   | 20010424 | US 1999-295443   | 19990421 |
| DE 19918580 | A1   | 19991028 | DE 1999-19918580 | 19990423 |

PRIORITY APPLN. INFO.: JP 1998-112589 A 19980423

AB The compn. comprises (A) an epoxy resin (e.g., bisphenol A epoxy resin and triglycidyl isocyanurate), (B) a curing agent (e.g., hexahydrophthalic anhydride), (C) a silane coupling agent having epoxy, mercapto or amino group (e.g., .gamma.-glycidoxypropyltrimethoxysilane), and (D) a release agent having -(CH<sub>2</sub>CH<sub>2</sub>)<sub>m</sub>- and -(CH<sub>2</sub>CH<sub>2</sub>O)<sub>n</sub>- group (m = 8-100 and n = integer; e.g., polyoxyethylene monopentacontyl ether).



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IT 146189-72-2P

RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM  
(Technical or engineered material use); PREP (Preparation); USES (Uses)  
(epoxy resin compns. having good mold release properties and  
**adhesion** for packaging optical semiconductor devices)

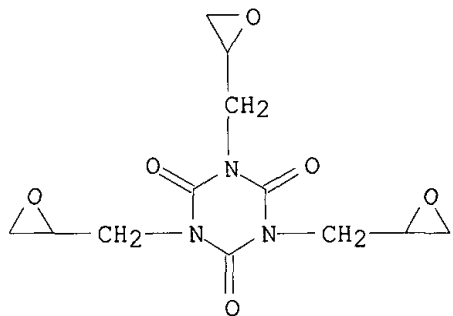
RN 146189-72-2 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-,  
polymer with (chloromethyl)oxirane, hexahydro-1,3-isobenzofurandione and  
4,4'-(1-methylethylidene)bis[phenol] (9CI) (CA INDEX NAME)

CM 1

CRN 2451-62-9

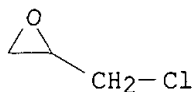
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CM 2

CRN 106-89-8

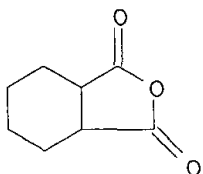
CMF C3 H5 Cl O



CM 3

CRN 85-42-7

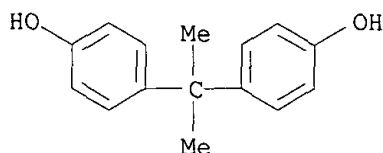
CMF C8 H10 O3



CM 4

CRN 80-05-7

CMF C15 H16 O2



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L4 ANSWER 10 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1995:183959 CAPLUS

DOCUMENT NUMBER: 122:134952

TITLE: One-component epoxy resin compositions

INVENTOR(S): Ikeda, Hisao; Gunji, Yasuhiro

PATENT ASSIGNEE(S): Nissan Chemical Ind Ltd, Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

|    | PATENT NO.  | KIND | DATE     | APPLICATION NO. | DATE     |
|----|---|------|----------|-----------------|----------|
|    | JP 06192396   | A2   | 19940712 | JP 1992-346351  | 19921225 |
| AB | Comps. with good heat resistance, dielec. properties, and storage stability at room temp., useful for <b>adhesives</b> , laminates, etc., of <b>electronic</b> parts, comprise (A) 100 parts low-m.p. isomers found in tris(2,3-epoxypropyl) isocyanurate (I) with m.p. 98-107.degree. and epoxy equiv. wt. 105, (B) 10-150 parts bisphenol epoxy resins liq. at room temp., (C) 0.7-1.1 equiv (vs. total epoxy groups) liq. polycarboxylic acid anhydrides, and (D) 0.1-5% (on total epoxy) acetylacetone complex of Co or Al. Thus, I fraction (m.p. 98-107.degree., epoxy equiv. wt. 100) 50, Epikote 828 50, methylhimic anhydride 122, and Co tris(acetylacetone) 0.4 part were mixed to obtain a compn. showing storage stability >90 days at 23.degree., which was heated to give cured products showing glass-transition temp. 231.degree. and vol. resistivity at 23.degree. 80 .times. 10 <sup>15</sup> .OMEGA.-cm. |      |          |                 |          |
| IT | <b>146189-70-0P 161220-61-7P</b>  |      |          |                 |          |
|    | RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)<br>(epoxy resin one-component comps. with good heat resistance and storage stability and elec. properties)  |      |          |                 |          |
| RN | 146189-70-0 CAPLUS  |      |          |                 |          |
| CN | 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with (chloromethyl)oxirane, 4,4'-(1-methylethylidene)bis[phenol] and (3a.alpha.,4.beta.,7.beta.,7a.alpha.)-3a,4,7,7a-tetrahydromethyl-4,7-methanoisobenzofuran-1,3-dione (9CI) (CA INDEX NAME)  |      |          |                 |          |

CM 1

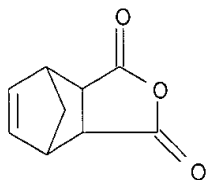
CRN 53584-57-9

CMF C10 H10 O3

CCI IDS

CDES \*

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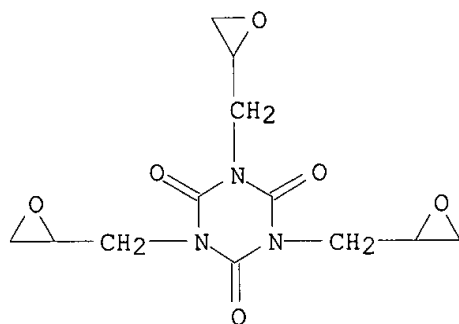


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CM 2

CRN 2451-62-9

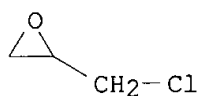
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CM 3

CRN 106-89-8

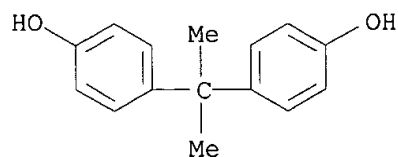
CMF C3 H5 Cl O



CM 4

CRN 80-05-7

CMF C15 H16 O2



RN 161220-61-7 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with (chloromethyl)oxirane, hexahydromethyl-1,3-isobenzofurandione and 4,4'-(1-methylethylidene)bis[phenol] (9CI) (CA INDEX NAME)

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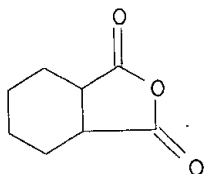
CM 1

CRN 25550-51-0

CMF C9 H12 O3

CCI IDS

CDES 8:ID

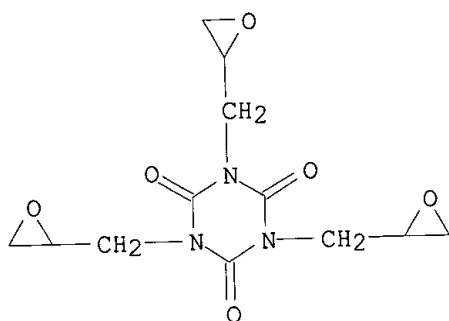


D1-Me

CM 2

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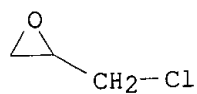
CMF C12 H15 N3 O6



CM 3

CRN 106-89-8

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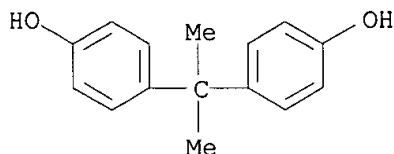


CM 4

CRN 80-05-7

CMF C15 H16 O2

09719844



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L4 ANSWER 11 OF 11 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1990:553934 CAPLUS

DOCUMENT NUMBER: 113:153934

TITLE: Cured glycidyl isocyanurate resins transparent to UV

INVENTOR(S): Sagami, Yosuke; Inagaki, Akihiro; Kajiwara, Yozo;

Yoshigahara, Haruyuki

PATENT ASSIGNEE(S): Hysol Japan, Ltd., Japan

SOURCE: Eur. Pat. Appl., 8 pp.

CODEN: EPXXDW

DOCUMENT TYPE: Patent

LANGUAGE: English

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

| PATENT NO.  | KIND | DATE     | APPLICATION NO. | DATE     |
|---|------|----------|-----------------|----------|
| EP 355728   | A2   | 19900228 | EP 1989-115239  | 19890818 |
| EP 355728   | A3   | 19901219 |                 |          |
| R: AT, BE, CH, DE, ES, FR, GB, GR, IT, LI, LU, NL, SE |      |          |                 |          |
| JP 02187421   | A2   | 19900723 | JP 1989-210175  | 19890816 |
| PRIORITY APPLN. INFO.:                                |      |          | JP 1988-205786  | 19880819 |

AB The title resins have good strength, toughness, and moisture resistance, and are useful for sealing UV-sensitive **electronic** devices or as transparent substrates, coatings, inks, **adhesives**, or lenses (no data). Thus, a UV-sensitive 64K erasable programmable read-only memory (EPROM) was dip-coated with a compn. of triglycidyl isocyanurate, hexahydrophthalic anhydride, and BuOH, dried, baked at 150.degree., and postcured at 50.degree. to give a device which showed no loss of data or UV erasability after 1000 h at 85.degree. and 85% humidity or 800 thermal cycles between -40.degree. and +80.degree..

IT **28825-96-9P**, Triglycidyl isocyanurate homopolymer  
**57602-00-3P 129825-75-8P 129825-76-9P**  
**129825-77-0P**

RL: PREP (Preparation)

(UV-transparent, manuf. of)

RN 28825-96-9 CAPLUS

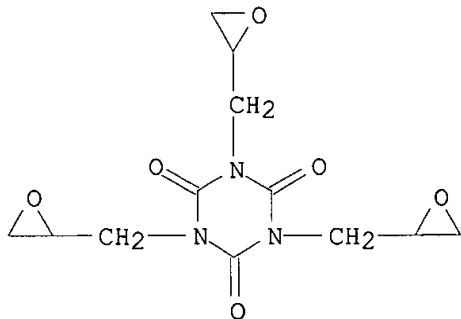
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, homopolymer (9CI) (CA INDEX NAME)

CM 1

CRN 2451-62-9

CMF C12 H15 N3 O6

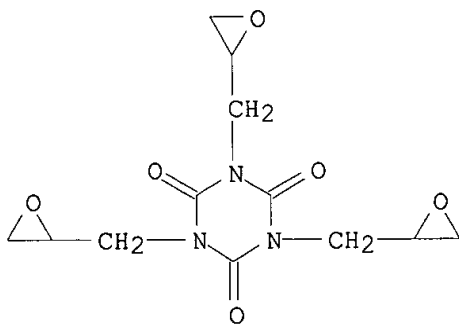
09719844



RN 57602-00-3 CAPLUS  
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-,  
polymer with hexahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

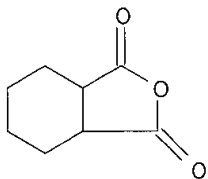
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CRN 2451-62-9  
CMF C12 H15 N3 O6



CM 2

CRN 85-42-7  
CMF C8 H10 O3



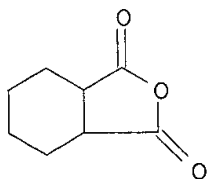
RN 129825-75-8 CAPLUS  
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polymer with hexahydromethyl-1,3-isobenzofurandione and  
2,2'-[(1-methylethylidene)bis(4,1-cyclohexanediylloxymethylene)]bis[oxirane  
(9CI) (CA INDEX NAME)

CM 1

CRN 25550-51-0  
CMF C9 H12 O3  
CCI IDS

09719844

CDES 8:ID

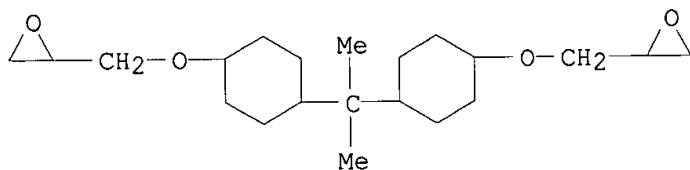


D1-Me

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CRN 13410-58-7

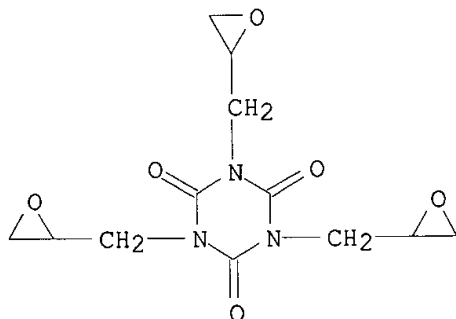
CMF C21 H36 O4



CM 3

CRN 2451-62-9

CMF C12 H15 N3 O6



RN 129825-76-9 CAPLUS

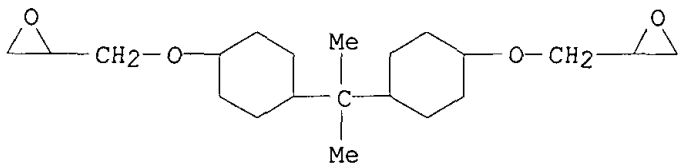
CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with N-(2-aminoethyl)-N'-[2-[(2-aminoethyl)amino]ethyl]-1,2-ethanediamine and 2,2'-[(1-methylethylidene)bis(4,1-cyclohexanediyloxymethylene)]bis[oxirane] (9CI) (CA INDEX NAME)

CM 1

CRN 13410-58-7

CMF C21 H36 O4

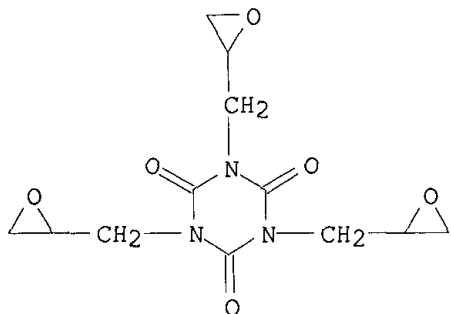
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CM 2

CRN 2451-62-9

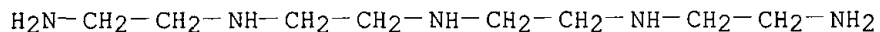
CMF C12 H15 N3 O6



CM 3

CRN 112-57-2

CMF C8 H23 N5



RN 129825-77-0 CAPLUS

1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(oxiranylmethyl)-, polymer with hexahydromethyl-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

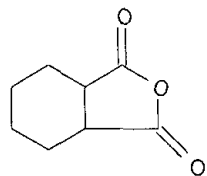
CM 1

CRN 25550-51-0

CMF C9 H12 O3

CCI IDS

CDES 8:ID



D1—Me

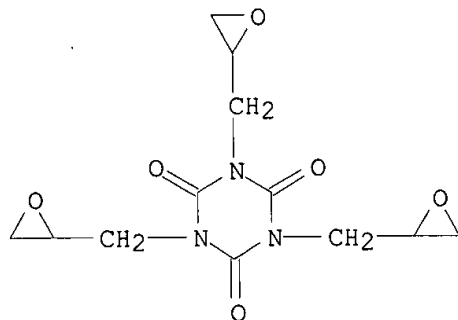


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CM 2

CRN 2451-62-9

CMF C12 H15 N3 O6



=>

---Logging off of STN---

=>

Executing the logoff script...

=> LOG Y

|  |            |         |
|--|------------|---------|
| COST IN U.S. DOLLARS                       | SINCE FILE | TOTAL   |
|  | ENTRY      | SESSION |
| FULL ESTIMATED COST                        | 57.12      | 197.61  |
| DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS) | SINCE FILE | TOTAL   |
|  | ENTRY      | SESSION |
| CA SUBSCRIBER PRICE                        | -6.82      | -6.82   |

STN INTERNATIONAL LOGOFF AT 18:28:39 ON 13 MAY 2002

09719844

Welcome to STN International! Enter x:x

LOGINID:sssptal712mxf

PASSWORD:

TERMINAL (ENTER 1, 2, 3, OR ?):2

\* \* \* \* \* Welcome to STN International \* \* \* \* \*

NEWS Web Page URLs for STN Seminar Schedule - N. America  
NEWS 2 Jan 25 BLAST(R) searching in REGISTRY available in STN on the Web  
NEWS 3 Jan 29 FSTA has been reloaded and moves to weekly updates  
NEWS 4 Feb 01 DKILIT now produced by FIZ Karlsruhe and has a new update frequency  
NEWS 5 Feb 19 Access via Tymnet and SprintNet Eliminated Effective 3/31/02  
NEWS 6 Mar 08 Gene Names now available in BIOSIS  
NEWS 7 Mar 22 TOXLIT no longer available  
NEWS 8 Mar 22 TRCTHERMO no longer available  
NEWS 9 Mar 28 US Provisional Priorities searched with P in CA/CAPLUS and USPATFULL  
NEWS 10 Mar 28 LIPINSKI/CALC added for property searching in REGISTRY  
NEWS 11 Apr 02 PAPERCHEM no longer available on STN. Use PAPERCHEM2 instead.  
NEWS 12 Apr 08 "Ask CAS" for self-help around the clock  
NEWS 13 Apr 09 BEILSTEIN: Reload and Implementation of a New Subject Area  
NEWS 14 Apr 09 ZDB will be removed from STN  
NEWS 15 Apr 19 US Patent Applications available in IFICDB, IFIPAT, and IFIUDB  
NEWS 16 Apr 22 Records from IP.com available in CAPLUS, HCAPLUS, and ZCAPLUS  
NEWS 17 Apr 22 BIOSIS Gene Names now available in TOXCENTER  
NEWS 18 Apr 22 Federal Research in Progress (FEDRIP) now available  
  
NEWS EXPRESS February 1 CURRENT WINDOWS VERSION IS V6.0d, CURRENT MACINTOSH VERSION IS V6.0a(ENG) AND V6.0Ja(JP), AND CURRENT DISCOVER FILE IS DATED 05 FEBRUARY 2002  
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NEWS INTER General Internet Information  
NEWS LOGIN Welcome Banner and News Items  
NEWS PHONE Direct Dial and Telecommunication Network Access to STN  
NEWS WWW CAS World Wide Web Site (general information)

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\* \* \* \* \* STN Columbus \* \* \* \* \*

FILE 'HOME' ENTERED AT 18:39:20 ON 13 MAY 2002

=> file registry  
COST IN U.S. DOLLARS  
  
FULL ESTIMATED COST

| SINCE FILE | TOTAL   |
|------------|---------|
| ENTRY      | SESSION |
| 0.21       | 0.21    |

09719844

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STRUCTURE FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4  
DICTIONARY FILE UPDATES: 12 MAY 2002 HIGHEST RN 414856-11-4

TSCA INFORMATION NOW CURRENT THROUGH July 7, 2001

Please note that search-term pricing does apply when  
conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Calculated physical property data is now available. See HELP PROPERTIES  
for more information. See STNote 27, Searching Properties in the CAS  
Registry File, for complete details:  
<http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf>

=>

Uploading 09543628b.str

L1 STRUCTURE UPLOADED

=> s full l1

FULL SEARCH INITIATED 18:40:50 FILE 'REGISTRY'  
FULL SCREEN SEARCH COMPLETED - 3372 TO ITERATE

100.0% PROCESSED 3372 ITERATIONS 1206 ANSWERS  
SEARCH TIME: 00.00.01

L2 1206 SEA SSS FUL L1

=> file caplus

| COST IN U.S. DOLLARS | SINCE FILE<br>ENTRY | TOTAL<br>SESSION |
|----------------------|---------------------|------------------|
| FULL ESTIMATED COST  | 140.66              | 140.87           |

FILE 'CAPLUS' ENTERED AT 18:40:54 ON 13 MAY 2002  
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FILE COVERS 1907 - 13 May 2002 VOL 136 ISS 20  
FILE LAST UPDATED: 10 May 2002 (20020510/ED)

This file contains CAS Registry Numbers for easy and accurate  
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CAS roles have been modified effective December 16, 2001. Please check your SDI profiles to see if they need to be revised. For information on CAS roles, enter HELP ROLES at an arrow prompt or use the CAS Roles thesaurus (/RL field) in this file.

=> s l2 and electronic and (adhesive or adhesion)

1372 L2  
 363585 ELECTRONIC  
 21498 ELECTRONICS  
 378840 ELECTRONIC  
 (ELECTRONIC OR ELECTRONICS)  
 141668 ADHESIVE  
 92659 ADHESIVES  
 160378 ADHESIVE  
 (ADHESIVE OR ADHESIVES)  
 200551 ADHESION  
 2593 ADHESIONS  
 201407 ADHESION  
 (ADHESION OR ADHESIONS)

L3 0 L2 AND ELECTRONIC AND (ADHESIVE OR ADHESION)

=> s l2 and electronic

1372 L2  
 363585 ELECTRONIC  
 21498 ELECTRONICS  
 378840 ELECTRONIC  
 (ELECTRONIC OR ELECTRONICS)

L4 6 L2 AND ELECTRONIC

=> d ibib abs hitstr 1

L4 ANSWER 1 OF 6 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 2001:136798 CAPLUS

DOCUMENT NUMBER: 134:194125

TITLE: Meltable resins based on unsaturated polyesters and their use

INVENTOR(S): Lienert, Klaus-Wilhelm; Hegemann, Guenter; Eichhorst, Manfred

PATENT ASSIGNEE(S): Schenectady International Inc., USA

SOURCE: Ger. Offen., 12 pp.

CODEN: GWXXBX

DOCUMENT TYPE: Patent

LANGUAGE: German

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

| PATENT NO.    | KIND | DATE     | APPLICATION NO.  | DATE     |
|---------------|------|----------|------------------|----------|
| DE 19939759   | A1   | 20010222 | DE 1999-19939759 | 19990821 |
| WO 2001014473 | A1   | 20010301 | WO 2000-EP7381   | 20000731 |

W: KR, US

RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE

PRIORITY APPLN. INFO.: DE 1999-19939759 A 19990821

AB Compns. with low m.p., good storage stability in the solid state, and fast curability in the melt state contain (A) .gtoreq.1 solid unsatd. polyester and (B) .gtoreq.1 oligomer and(or) polymer having terminal and(or) side propenyl, isopropenyl and(or) (meth)acrylate ester groups as crosslinkers for the unsatd. polyesters. These compns. are useful in the manuf. of coatings and cast moldings, and as impregnants for in the manuf. of **electronic** parts. A typical (B) was manufd. by heating a mixt. contg. adipic acid 1753.7, isoprenol 478.6, hydrogenated bisphenol A

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368.4, THEIC 261.7, PhMe 400, and Sn catalyst 6 g 3 h at 130.degree. under N, heating the mixt. to 190.degree. in 2 h, and heating 4 h at 190.degree..

IT 327969-22-2P

RL: IMF (Industrial manufacture); MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PREP (Preparation); PROC (Process); USES (Uses)

(crosslinker; meltable resins based on unsatd. polyesters and oligomers or polymers having isoprenyl, propenyl, or (meth)acrylate groups as crosslinkers)

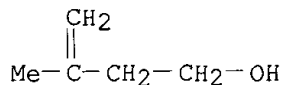
RN 327969-22-2 CAPLUS

CN Hexanedioic acid, polymer with 4,4'-(1-methylethylidene)bis[cyclohexanol] and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione, 3-methyl-3-butenyl ester (9CI) (CA INDEX NAME)

CM 1

CRN 763-32-6

CMF C5 H10 O



CM 2

CRN 327969-21-1

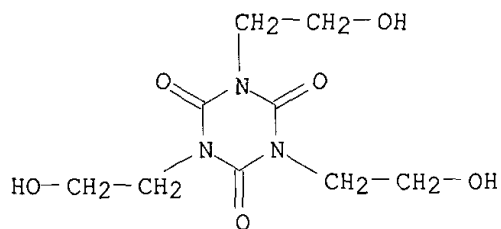
CMF (C15 H28 O2 . C9 H15 N3 O6 . C6 H10 O4)x

CCI PMS

CM 3

CRN 839-90-7

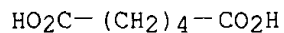
CMF C9 H15 N3 O6



CM 4

CRN 124-04-9

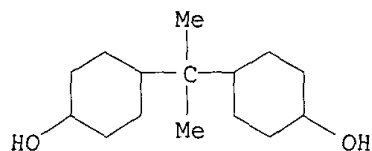
CMF C6 H10 O4



CM 5

09719844

CRN 80-04-6  
CMF C15 H28 O2



=> d ibib abs hitstr 2

L4 ANSWER 2 OF 6 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1998:314230 CAPLUS

DOCUMENT NUMBER: 128:325252

TITLE: Soldering flux containing tris(2-hydroxypropyl)isocyanurate

INVENTOR(S): Ikeda, Hisao; Oosawa, Kenichi; Koda, Toshinari

PATENT ASSIGNEE(S): Nissan Chemical Industries, Ltd., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.

CODEN: JKXXAF

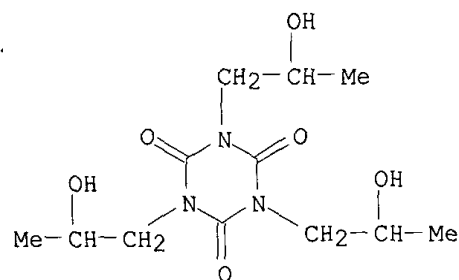
DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

|    | PATENT NO.   | KIND | DATE     | APPLICATION NO. | DATE     |
|----|--|------|----------|-----------------|----------|
|    | JP 10128577  | A2   | 19980519 | JP 1996-280606  | 19961023 |
| AB | A soldering flux contains tris(2-hydroxypropyl)isocyanurate for improved reliability of soldered joints in <b>electronics</b> . A paste solder contains the flux and a metal powder having a m.p. of 40-450.degree.. |      |          |                 |          |
| IT | <b>4885-66-9</b> , Tris(2-hydroxypropyl)isocyanurate<br>RL: MOA (Modifier or additive use); USES (Uses)<br>(soldering flux contg. tris(2-hydroxypropyl)isocyanurate)   |      |          |                 |          |
| RN | 4885-66-9 CAPLUS   |      |          |                 |          |
| CN | 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(2-hydroxypropyl)- (9CI)<br>(CA INDEX NAME)   |      |          |                 |          |



=> d ibib abs hitstr 3

L4 ANSWER 3 OF 6 CAPLUS COPYRIGHT 2002 ACS

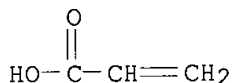
ACCESSION NUMBER: 1987:167274 CAPLUS

DOCUMENT NUMBER: 106:167274

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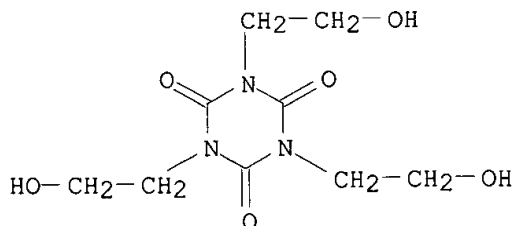
TITLE: UV-cured flexible polyester-monoacrylate protective thermistor coatings having good edge coverage and a method of coating  
INVENTOR(S): Hudock, John S.  
PATENT ASSIGNEE(S): Westinghouse Electric Corp., USA  
SOURCE: U.S., 7 pp.  
CODEN: USXXAM  
DOCUMENT TYPE: Patent  
LANGUAGE: English  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

|     | PATENT NO.   | KIND | DATE     | APPLICATION NO. | DATE     |
|-----|--|------|----------|-----------------|----------|
|     | -----  | ---  | -----    | -----           | -----    |
|     | US 4623559   | A    | 19861118 | US 1985-755134  | 19850712 |
| AB  | <b>Electronic</b> components such as thermistors are coated with a liq. resin compn. contg. a polyester-methacrylate and a photoinitiator. The components are axially rotated to control dripping and subjected to UV radiation to cure the resin. Coatings displaying good crack resistance, flexibility, thermal stability, and edge coverage were obtained. |      |          |                 |          |
| IT  | <b>107721-32-4</b><br>RL: USES (Uses)<br>(UV-curable coating compn. contg., for <b>electronic</b> components)  |      |          |                 |          |
| RN  | 107721-32-4 CAPLUS   |      |          |                 |          |
| CN  | 1,4-Benzenedicarboxylic acid, polymer with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione, 2-propenoate (9CI) (CA INDEX NAME)  |      |          |                 |          |
| CM  | 1  |      |          |                 |          |
| CRN | 79-10-7  |      |          |                 |          |
| CMF | C3 H4 O2   |      |          |                 |          |



CM 2  
CRN 26337-62-2  
CMF (C9 H15 N3 O6 . C8 H6 O4)x  
CCI PMS

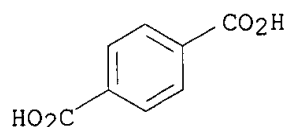
CM 3  
CRN 839-90-7  
CMF C9 H15 N3 O6



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CM 4

CRN 100-21-0  
CMF C8 H6 O4

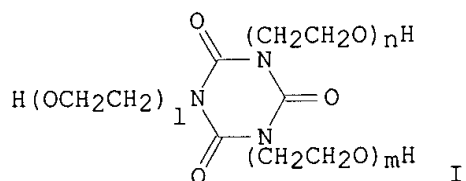


=> d ibib abs hitstr 4

L4 ANSWER 4 OF 6 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 1984:552919 CAPLUS  
DOCUMENT NUMBER: 101:152919  
TITLE: Thermosetting resin compositions  
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan  
SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.  
CODEN: JKXXAF  
DOCUMENT TYPE: Patent  
LANGUAGE: Japanese  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

| PATENT NO.  | KIND | DATE     | APPLICATION NO. | DATE     |
|-------------|------|----------|-----------------|----------|
| JP 59080416 | A2   | 19840509 | JP 1982-191149  | 19821029 |
| JP 60017447 | B4   | 19850502 |                 |          |

GI



AB Thermosetting resin compns. are composed of (1) a bisphenol epoxy resin unsatd. acid ester, (2) an isocyanurate obtained by esterification of I (1, m, n = 1, 2) with a monobasic unsatd. acid or its lower alkyl ester, and (3) other monomer(s) if necessary. Optionally, a polyisocyanate is also added to the compn. The compns. exhibit good hardening properties and workability, and give cured products having good heat resistance, water resistance, and high mech. strength. The compns. are esp. useful in fabrication and coating of **electronic** devices. Thus, an ester prepd. from methacrylic acid 2.00, Epikote 828 0.40, and Epikote 1001 0.60 mol was mixed 70:30 with styrene, while 70 parts acrylic acid ester of I (1 = m = n = 1) was dissolved in 30 parts styrene. The 2 solns. in 9:1 ratio were then mixed with 1% benzoyl peroxide and formed into a sheet (cured at 80.degree., with after-cure treatment at 120.degree.), which showed bending strength 13.0 kg/mm<sup>2</sup> and thermal deformation temp. 120.degree. (JIS K 6911).

IT 88403-03-6 88403-04-7



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RL: MOA (Modifier or additive use); USES (Uses)  
(crosslinking agents, for epoxy resin methacrylates)

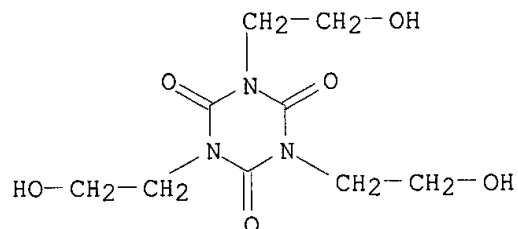
RN 88403-03-6 CAPLUS

CN 2-Propenoic acid, ester with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 839-90-7

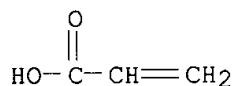
CMF C9 H15 N3 O6



CM 2

CRN 79-10-7

CMF C3 H4 O2



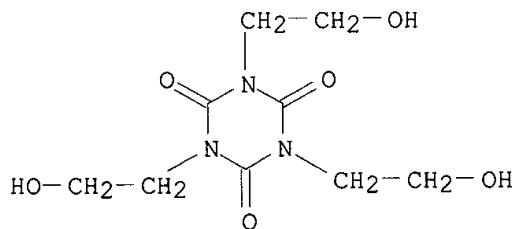
RN 88403-04-7 CAPLUS

CN 2-Propenoic acid, 2-methyl-, ester with 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 839-90-7

CMF C9 H15 N3 O6

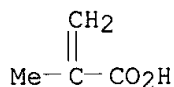


CM 2

CRN 79-41-4

CMF C4 H6 O2

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=> d ibib abs hitstr 5

L4 ANSWER 5 OF 6 CAPLUS COPYRIGHT 2002 ACS  
ACCESSION NUMBER: 1981:463137 CAPLUS  
DOCUMENT NUMBER: 95:63137  
TITLE: **Electronic** insulators  
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan  
SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.  
CODEN: JKXXAF  
DOCUMENT TYPE: Patent  
LANGUAGE: Japanese  
FAMILY ACC. NUM. COUNT: 1  
PATENT INFORMATION:

| PATENT NO.  | KIND | DATE     | APPLICATION NO. | DATE     |
|-------------|------|----------|-----------------|----------|
| JP 56013607 | A2   | 19810210 | JP 1979-89656   | 19790713 |
| JP 57033643 | B4   | 19820719 |                 |          |

AB An elec. insulator resin compn. comprises the reaction product of a polybasic carboxylic acid or its deriv. (.gtoreq.50 equiv % of total carboxyl groups from terephthalic or isophthalic acid or their dialkyl esters) with a dihydric and a polyhydric alc. (functionality .gtoreq.3) and .apprx.5-30% (on reaction product) of a polyamide resin, which are heated until the mixt. remains transparent and homogeneous at room temp. Thus, ethylene glycol 119, glycerol 78, di-Me terephthalate 506, and Pb(OAc)2 0.71 g were heated at 150-240.degree.. To a soln. of the reaction product (155 g) in 1313 g cresol, 27 g nylon 12 [24937-16-4] (Daiamide L-1640) was added, and the mixt. was heated at 130.degree. for 3 h, at 160.degree. for .apprx.8 h [after addn. of 11 g Ti(OBu)4], and at 160.degree. for .apprx.2 h until the soln. remained clear at room temp. After addn. of 16 g Ti(OBu)4 and 9 g Zn naphthenate, the soln. remained homogeneous and transparent for 20 days at room temp.

IT 31045-37-1

RL: USES (Uses)

(elec. insulators, contg. polyamides, room temp. stability of solns. of)

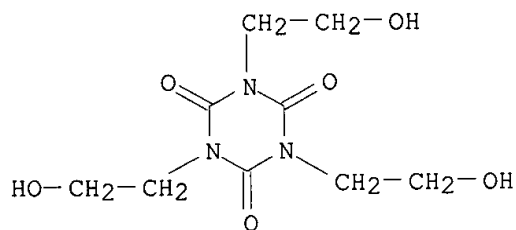
RN 31045-37-1 CAPLUS

CN 1,4-Benzenedicarboxylic acid, dimethyl ester, polymer with 1,2-ethanediol and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI)  
(CA INDEX NAME)

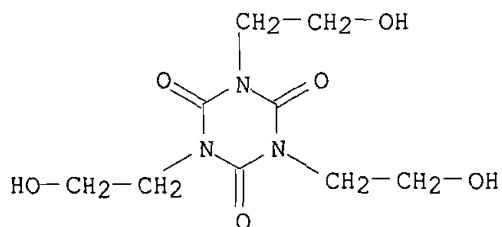
CM 1

CRN 839-90-7

CMF C9 H15 N3 O6

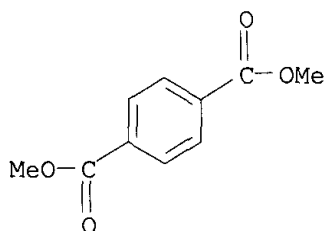


09719844



CM 2

CRN 120-61-6  
CMF C10 H10 O4



CM 3

CRN 107-21-1  
CMF C2 H6 O2

HO-CH<sub>2</sub>-CH<sub>2</sub>-OH

=> d ibib abs hitstr 6

L4 ANSWER 6 OF 6 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1976:495178 CAPLUS

DOCUMENT NUMBER: 85:95178

TITLE: Hardenable, heat-resistant unsaturated polyester resins, especially for use in the **electronics** industry

INVENTOR(S): Janssen, Harald; Hegemann, Guenther

PATENT ASSIGNEE(S): Beck, Dr., und Co. A.-G., Ger.

SOURCE: Ger. Offen., 12 pp.

CODEN: GWXXBX

DOCUMENT TYPE: Patent

LANGUAGE: German

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

| PATENT NO. | KIND | DATE     | APPLICATION NO. | DATE     |
|------------|------|----------|-----------------|----------|
| DE 2460768 | A1   | 19760701 | DE 1974-2460768 | 19741221 |
| DE 2460768 | B2   | 19810409 |                 |          |
| DE 2460768 | C3   | 19820408 |                 |          |
| ES 442941  | A1   | 19770801 | ES 1975-442941  | 19751125 |

|             |    |          |                |          |
|-------------|----|----------|----------------|----------|
| NL 7514640  | A  | 19760623 | NL 1975-14640  | 19751216 |
| NL 169598   | B  | 19820301 |                |          |
| NL 169598   | C  | 19820802 |                |          |
| FR 2295051  | A1 | 19760716 | FR 1975-38899  | 19751218 |
| FR 2295051  | B1 | 19800523 |                |          |
| SE 7514478  | A  | 19760622 | SE 1975-14478  | 19751219 |
| SE 417832   | B  | 19810413 |                |          |
| SE 417832   | C  | 19810730 |                |          |
| JP 51089592 | A2 | 19760805 | JP 1975-150753 | 19751219 |
| JP 55046405 | B4 | 19801122 |                |          |

## PRIORITY APPLN. INFO.:

DE 1974-2460768 19741221

AB The polyester resins were prepd. from tetrahydrophthalic anhydride (I), H<sub>2</sub>NCH<sub>2</sub>CH<sub>2</sub>OH, maleic anhydride (II), neopentyl glycol (III), tris(hydroxyethyl) isocyanurate (IV), or tris(2-carboxyethyl) isocyanurate, and, in one case, Ampol 1022 (dimerized fatty acids). Styrene solns. of the resins have a satisfactory pot life. Thus, 550 g I and 221.6 g H<sub>2</sub>NCH<sub>2</sub>CH<sub>2</sub>OH were heated <130.degree., freed of water in vacuo, mixed with II 476, III 380, Empol 1022 1092, IV 316.8, and hydroquinone 0.4 g, and heated at .ltoreq.210.degree. to give a product with acid no. <25, and the resin was mixed with styrene and 2% Me Et ketone peroxide to prepare a resin with gel time 15 min. The hardened resin was heated 7 days at 250.degree. with wt. loss 6.9%.

IT 60262-73-9 60262-74-0

RL: USES (Uses)

(styrene-crosslinked, heat-resistant, elec. insulators)

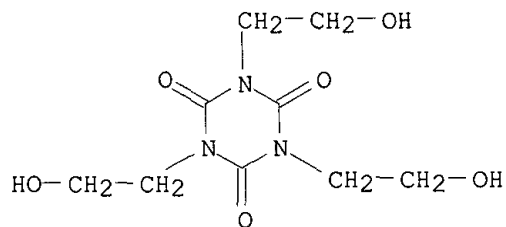
RN 60262-73-9 CAPLUS

CN 9,12-Octadecadienoic acid (9Z,12Z)-, dimer, polymer with 2-aminoethanol, 2,2-dimethyl-1,3-propanediol, 2,5-furandione, 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione and 1,3,5-tris(2-hydroxyethyl)-1,3,5-triazine-2,4,6(1H,3H,5H)-trione (9CI) (CA INDEX NAME)

CM 1

CRN 839-90-7

CMF C9 H15 N3 O6



CM 2

CRN 141-43-5

CMF C2 H7 N O

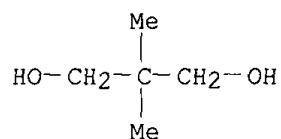
H<sub>2</sub>N-CH<sub>2</sub>-CH<sub>2</sub>-OH

CM 3

CRN 126-30-7

CMF C5 H12 O2

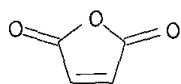
09719844



CM 4

CRN 108-31-6

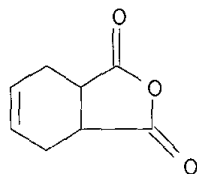
CMF C4 H2 O3



CM 5

CRN 85-43-8

CMF C8 H8 O3



CM 6

CRN 6144-28-1

CMF (C18 H32 O2)2

CCI PMS

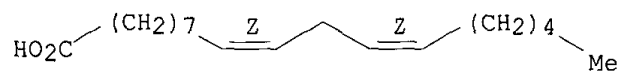
CM 7

CRN 60-33-3

CMF C18 H32 O2

CDGS 2:Z,Z

Double bond geometry as shown.



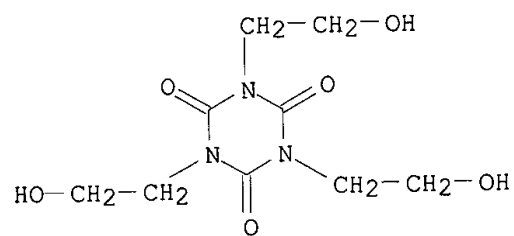
RN 60262-74-0 CAPLUS

CN 1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, 1,3,5-tris(2-hydroxyethyl)-, polymer with 2-aminoethanol, 2,2-dimethyl-1,3-propanediol, 2,5-furandione and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione (9CI) (CA INDEX NAME)

CM 1

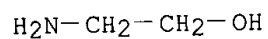
09719844

CRN 839-90-7  
CMF C9 H15 N3 O6



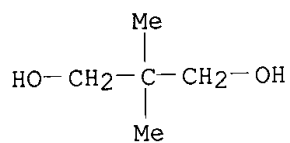
CM 2

CRN 141-43-5  
CMF C2 H7 N O



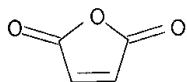
CM 3

CRN 126-30-7  
CMF C5 H12 O2



CM 4

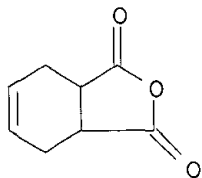
CRN 108-31-6  
CMF C4 H2 O3



CM 5

CRN 85-43-8  
CMF C8 H8 O3

09719844



=>

---Logging off of STN---

=>

Executing the logoff script...

=> LOG Y

|  |            |         |
|--|------------|---------|
| COST IN U.S. DOLLARS                       | SINCE FILE | TOTAL   |
|  | ENTRY      | SESSION |
| FULL ESTIMATED COST                        | 36.01      | 176.88  |
| DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS) | SINCE FILE | TOTAL   |
|  | ENTRY      | SESSION |
| CA SUBSCRIBER PRICE                        | -3.72      | -3.72   |

STN INTERNATIONAL LOGOFF AT 18:45:56 ON 13 MAY 2002